Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: B = .004” X .0042” E = .004” X .0055”**

**Backside Potential:**

**Mask Ref: BTB**

**APPROVED BY: DK DIE SIZE .016” X .017” DATE: 10/4/21**

**MFG: ALLEGRO / SPRAGUE THICKNESS .006” P/N: 2N3251**

**DG 10.1.2**

#### Rev B, 7/19/02